

FORTRON[®] 6150T4

Polyphenylene sulfide

Fortron 6150T4 is a 50% glass-fiber reinforced and mineral-filled grade with improved impact and thermal shock resistance.

Product information Resin Identification Part Marking Code	PPS-I-(GF+MD)50 >PPS-I-(GF+MD)		ISO 1043 ISO 11469
Rheological properties Moulding shrinkage, parallel Moulding shrinkage, normal	0.2 0.5		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties Tensile modulus Tensile stress at break, 5mm/min Tensile strain at break, 5mm/min Flexural modulus Flexural strength Charpy impact strength, 23°C Charpy notched impact strength, 23°C Poisson's ratio [C]: Calculated	1.7 15500 260 50	MPa %	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 178 ISO 179/1eU ISO 179/1eA
Thermal properties Melting temperature, 10°C/min Glass transition temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel Coefficient of linear thermal expansion (CLTE), normal		°C	ISO 11357-1/-3 ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2 ISO 11359-1/-2
Flammability Burning Behav. at 1.5mm nom. thickn. Thickness tested Glow Wire Flammability Index, 1.0mm Glow Wire Flammability Index, 2.0mm Glow Wire Ignition Temperature, 1.0mm Glow Wire Ignition Temperature, 2.0mm [OT]: One time tested [1]: SR 01407577 Case Salesforce 24COR032B _Glow Wire	1.5 960 ^[OT, 1] 960 ^[OT, 1] 775 ^[OT, 1] 825 ^[OT, 1]	°C °C	IEC 60695-11-10 IEC 60695-11-10 IEC 60695-2-12 IEC 60695-2-12 IEC 60695-2-13 IEC 60695-2-13
Electrical properties Relative permittivity, 1000Hz Relative permittivity, 1MHz Dissipation factor, 1000Hz Dissipation factor, 1MHz		E-4 E-4	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1

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(+) **18816996168** Ponciplastics.com



Sim. to ISO 62 ISO 1183

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Physical/Other properties

Water absorption, 2mm		0.02	0/_
•			
Density		1720	kg/m³
Injection			
Drying Recommended		yes	
Drying Temperature		130	°C
Drying Time, Dehumidified Dryer		2 - 4	h
Processing Moisture Content		≤0.02	%
Melt Temperature Optimum		330	°C
Min. melt temperature		310	°C
Max. melt temperature		340	°C
Screw tangential speed		0.2 - 0.3	m/s
Mold Temperature Optimum		150	°C
Min. mould temperature		140	°C
Max. mould temperature		160	°C
Hold pressure range		30 - 70	MPa
Back pressure		3	MPa
Characteristics			
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Processing	Injection Moulding
Delivery form	Pellets
Special characteristics	High impact or impact modified, Thermal shock resistant

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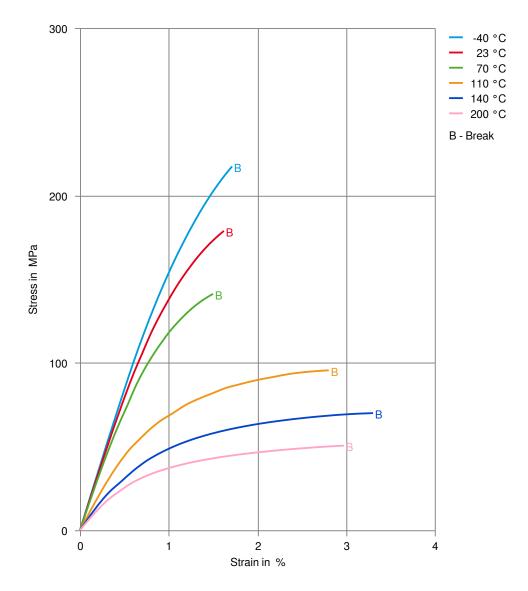




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Polyphenylene sulfide

Stress-strain



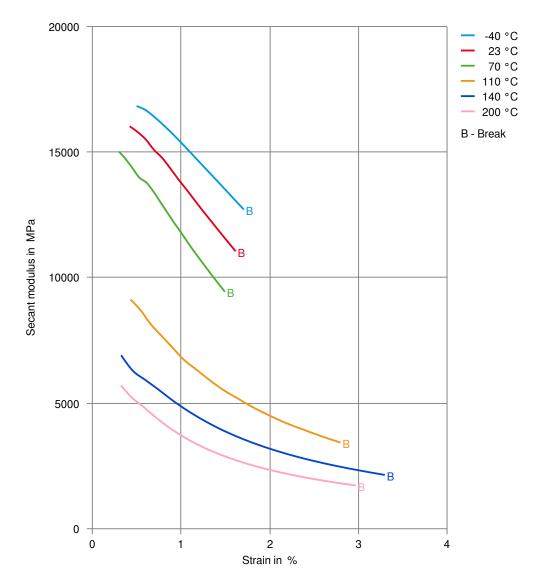




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Secant modulus-strain



Printed: 2025-05-30

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Revised: 2025-01-08 Source: Celanese Materials Database

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